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OCP APAC Summit Explores Challenges Facing Data Center Infrastructure

On August 11-12, the Open Compute Project (OCP) is bringing together APAC communities for a vspecial two-day, in-person summit to explore the many challenges and opportunities facing data center infrastructure, today and tomorrow. At the TaiNEX2 in Taipei City, Taiwan, the OCP APAC Summit will showcase the latest innovations and technical advancements from around the world, and feature talks from experts who are researching, designing, building and running the next generation of hyperscale data center facilities and infrastructure. The expo hall will bring together buyers and sellers from the entire ecosystem and supply chain.

The event theme for the 2026 OCP APAC Summit, "Leading the Future of AI," exemplifies the OCP Community's collaborations over the years that drive openness, efficiency, sustainability, scalability and growth, shaping the future of AI data centers, driving innovation across the global data center and edge technology ecosystem. With AI, the pace of technological evolution has increased dramatically and the collaborations within the OCP community have become central to enabling a rapid AI data center buildout.

Looking further into the future, the next wave of AI will be inference, with computations moving closer to the end user. With this in mind, the OCP community has begun working on an architecture, referred to as the AI Computing Continuum, which aims to accelerate the adoption of scalable, interoperable and sustainable AI systems beyond traditional hyperscale data centers, by defining open, modular infrastructure standards that work across diverse hyperscale adjacent environments—including regional colocation, enterprise on-premise, telco points of presence and industrial sites.

We are at a technology inflection point in the data center industry, driven by a large investment in AI data centers. There is a need to rethink data center IT equipment, facilities and silicon supply chains. Thus, the OCP community has expanded its Open Data Center Ecosystem Vision to include all elements of the data center, from grid to chip.

Through its Open Systems for AI strategic initiative, the OCP community is working on important technology advancements in (1) chiplet technology and associated advanced packaging, (2) in rack systems such as cooling and power distribution, networking and storage, server architectures and optical interconnect for scale-up networking, and (3) data center facility reference architectures that cover higher voltage, direct current distribution to the data hall, integrated telemetry and systems management between the facilities and data hall, and coordinated interactions with the power grid.

Looking further down the road, technologies that are still maturing will need to be leveraged to sustain the longer-term growth of AI and HPC systems. The Future Technologies Symposium, co-located at the 2026 OCP APAC Summit, is intended to include academics, researchers and startup companies that are bringing technology to market that will impact products in the next 2-5 years.

For more about the 2026 OCP APAC Summit see the website.

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